Overview

HP ProBook 450 G8 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Webcam LED (Optional)
- 3. HD Camera (Optional)
- 4. Camera Shutter (Only available with webcam)
- 5. Clickpad
- 6. SuperSpeed USB Type-A 5Gbps signaling rate port
- 7. Ethernet Port (RJ-45)
- 8. Nano Security Lock Slot (Lock sold separately)

Overview



Right

- 1. Power Button Key
- 2. Power Connector
- 3. SuperSpeed USB Type-C[®] 10Gbps signaling rate (USB 8. Power Delivery, DisplayPort[™] 1.4)
- 4. SuperSpeed USB Type-A 5Gbps signaling rate port
- 5. SuperSpeed USB Type-A 5Gbps signaling rateport
- HDMI Port (Cable not included)
- 7. Audio Combo Jack
- 8. Micro SD Card Reader
- 9. Touch Fingerprint Sensor (select models)

Overview

At a Glance

- A new compact design with lift-anywhere edge
- Choice of 11th generation Intel[®] Core[™] i7, i5 and i3 processors
- Preinstalled with Windows 10 versions or FreeDOS
- Optional NVIDIA GeForce MX450 discrete graphics with 2GB GDDR5 video memory
- Fast and upgradeable dual channel DDR4 SODIMM memory up to 32 GB
- Choice of 39.62 cm (15.6") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch screen, and Privacy Panel
 option
- to Features redesigned quiet and responsive HP Keyboard with numeric keypad, the HP Programmable key and backlit options
- Choice of solid state drives up to 1TB
- Multi-layered security with HP SureStart Gen6, HP Privacy Camera, HP Sure View Gen3 ¹, HP Sure Sense, HP Sure Click, and Touch Fingerprint reader ²
- Supports wireless options for connectivity on the go including gigabit-speed Wi-Fi 6 and CAT9 4G/LTE WWAN
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles ³
- Designed to support HP docking options including the HP Universal Dock G5
- Passed MIL-STD 810H tests⁴
- Battery life up to 12 hours and 30 minutes
- 1. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 2. Sold separately or as an optional feature
- 3.HP Notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
- 4. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP ProBook 450 G8 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64 – HP recommends Windows 10 Pro ¹

Windows 10 Pro 64 (National Academic only)2

Windows 10 Home 64¹

Windows 10 Home Single Language 641

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)¹

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

Supported Versions

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282.

PROCESSORS

Intel® Core™ i7-1185G7 (3.0 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores) 3.4 5.6

Intel® Core™ i7-1165G7 (2.8 GHz base frequency, up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores)

Intel® Core™ i5-1145G7 (2.6 GHz base frequency, up to 4.4 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) 3,45,6

Intel® Core™ i5-1135G7 (2.4 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) 3,45,6

Intel® Core™ i3-1125G4 with Intel® UHD Graphics (2.0 GHz base frequency, up to 3.7 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) 3.4 5.6

Intel® Core™ i3-1115G4 with Intel® UHD Graphics (3.0 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 2 cores) 3,45,6

Intel® Pentium® Gold 7505 with Intel® UHD Graphics (2.0 GHz base frequency, up to 3.5 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores) 3,4 5,6

Intel® Celeron® 6305 with Intel® UHD Graphics (1.8 GHz base frequency, 4 MB L3 cache, 2 cores) 3.45.6



Technical Specifications

Processors Family

11th Generation Intel® Core™ i7 processor (i7-1165G7)⁷
11th Generation Intel® Core™ i5 processor (i5-1135G7)⁷
11th Generation Intel® Core™ i3 processor (i3-1115G4)⁷

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.
- 7. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics (Core i5 and Core i7)³⁶ Intel® UHD Graphics (Core i3)

Discrete

NVIDIA® GeForce® MX450 (2 GB DDR5 dedicated) 9

Supports

Support HD decode, DX12, HDMI 1.4b 8

- 8. HD content required to view HD images.
- 9. Integrated graphics depends on processor. NVIDIA® Optimus™ technology requires an Intel processor, plus an NVIDIA® GeForce® discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA® Optimus™ technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).
- 36. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

DISPLAYS

Internal

Non-Touch

39.6 cm (15.6") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1366 x 768) 8,11
39.6 cm (15.6") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera (1366 x 768) 8,11



Technical Specifications

39.6 cm (15.6") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD+IR camera (1366 x 768)^{8,11} 39.6 cm (15.6") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera and WWAN (1366 x 768)^{8,11}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1920 x 1080) 8.11

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera (1920 x 1080)^{8,11}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD + IR camera (1920 x 1080)

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC for HD camera and WWAN (1920 x 1080) 8,11

39.6 cm (15.6") diagonal FHD UWVA eDP+PSR anti-glare, low power narrow bezel bent, 400 nits, 100% sRGB for HD camera (1920 x 1080) 8,11

39.6 cm (15.6") diagonal FHD UWVA eDP+PSR anti-glare, low power narrow bezel bent, 400 nits, 100% sRGB for HD+IR camera (1920 x 1080) ^{8,11}

39.6 cm (15.6") diagonal FHD UWVA eDP+PSR anti-glare, narrow bezel bent with HP Sure View Gen3 Integrated Privacy Screen, 1000 nits, 100% sRGB for HD camera (1920 x 1080) 8,11,12

39.6 cm (15.6") diagonal FHD UWVA eDP+PSR anti-glare, narrow bezel bent with HP Sure View Gen3 Integrated Privacy Screen, 1000 nits, 100% sRGB for HD+IR camera (1920 x 1080) 8,11,12

Touch

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare, narrow bezel bent, touch-on-panel screen, 250 nits, 45% NTSC for HD camera (1920 x 1080) 8,10,11

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare, narrow bezel bent touch-on-panel screen, 250 nits, 45% NTSC for HD camera and WWAN (1920 x 1080) 8,10,11

HDMI

Supports resolutions up to 4K 30Hz

- 8. HD content required to view HD images.
- 10. Sold separately or as an optional feature.
- 11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 12. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

NOTE: Actual brightness will be lower with touchscreen or Sure View.

STORAGE AND DRIVES

Primary M.2 Storage

128 GB PCIe® NVMe™ M.2 TLC Solid State Drive 13

256 GB PCIe® NVMe™ M.2 Value Solid State Drive 13

512 GB PCIe® NVMe™ M.2 Value Solid State Drive 13

512 GB Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10 13, 40,41

1 TB PCIe® NVMe™ M.2 TLC Solid State Drive 13

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

40. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.



Technical Specifications

41. Intel® Optane™ memory H10 only for Intel® PCIe® NVMe™ QLC M.2 SSD.

MEMORY

Maximum Memory

32 GB DDR4-3200 SDRAM 14

Memory

32 GB DDR4-3200 SDRAM (2 x 16 GB) ¹⁴
16 GB DDR4-3200 SDRAM (1 x 16 GB) ¹⁴
12 GB DDR4- 3200 SDRAM (4 GB and 8 GB (1 x 8 GB)) ¹⁴
8 GB DDR4-3200 SDRAM (1 x 8 GB) ¹⁴
8 GB DDR4-3200 SDRAM (2 x 4 GB) ¹⁴
4 GB DDR4-3200 SDRAM (1 x 4 GB) ¹⁴

Memory Slots

2 SODIMM

Both slots are accessible/upgradeable by IT or self-maintainers only

DDR4 PC4 SODIMMS, system runs at 3200

14. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Supports Dual Channel Memory

WLAN

Realtek 802.11ac (2x2) WLAN and Bluetooth® 5 Combo ¹⁵
Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® ¹⁵
Intel® Dual Band Wi-Fi® 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro® ¹⁸

WWAN

Intel® XMM™ 7360 LTE-Advanced (Cat9) 16

Ethernet

Realtek 10/100/1000 GbE NIC 17

- 15. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
- 16. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 17. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.
- 18. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it



Technical Specifications

may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers Integrated microphone (Dual Array)

Speaker Power

2W/4ohm Per speaker

Camera

720p HD Camera⁸
720p HD Camera+IR Camera ^{8,10}

8. HD content required to view HD images.

10. Sold separately or as an optional feature.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with numeric keypad and optional Durakeys and backlit

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

- F1 Display Switching
- F2 Blank or SureView On/Off
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Insert
- F11 Airplane Mode
- F12 Programmable Key

Print Screen

Power Button (with LED)

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software BIOS

HP BIOSphere Gen5 19

HP Drive Lock & Automatic Drive Lock

BIOS Update via Network

Power On Authentication

HP Secure Erase 21

Absolute Persistence Module 22

HP LAN-Wireless Protection

Pre-boot Authentication

Software

Xerox® DocuShare® 90 day free trial offer42

HP Connection Optimizer 20

HP Image Assistant

HP Hotkey Support

myHP

HP Noise Cancellation Software

HSA Fusion for Commercial



Technical Specifications

HSA Telemetry for Commercial

Touchpoint Customizer for Commercial

HP Notifications

HP Privacy Settings

HP System Information

HP Wireless Button Driver

HP Power Manager

HP Work Well

Buy Office (sold separately)

Manageability Features

HP Driver Packs (download) 23

HP Manageability Integration Kit Gen3 (download) 24

HP System Software Manager (SSM) (download)

HP BIOS Config Utility (BCU) (download)

HP Client Catalog (download)

HP Client Management Script Library (download)

Client Security Software

HP Client Security Manager Gen7 ²⁵ Windows Defender ²⁶

Security Management

Pre-boot Authentication

USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

HP Fingerprint Sensor 27

Support for chassis padlocks and cable lock devices

HP Sure Click 28

HP Sure Sense 30

HP Sure Start Gen6 31

HP Sure Admin 32

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2 Level 2 Certified) 33

19. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

20. HP Connection Optimizer requires Windows 10.

21. HP Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

22. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/

23. HP Driver Packs not preinstalled, however available for download at

http://www.hp.com/go/clientmanagement.

- 24. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 25. HP Client Security Manager Gen6 requires Windows and is available on the select HP Pro and Elite PCs.
- 26. Windows Defender Opt in and internet connection required for updates.



Technical Specifications

- 27. HP Fingerprint sensor is an optional feature that must be configured at purchase.
- 28. Windows Defender Opt in and internet connection required for updates.
- 29. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- 30. HP Sure Sense requires Windows 10 Pro or Enterprise.
- 31. HP Sure Start Gen6 is available on select HP PCs.
- 32. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- 33. Firmware TPM is version 2.0.
- 42. Simply sign up and start using Xerox® DocuShare® Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 day free trial period. See visit www.xerox.com/docusharego for details.

POWER

Power Supply 16

HP Smart 65 W External AC power adapter ³³ HP Smart 65 W EM External AC power adapter ³³ HP Smart 65 W USB Type-C® adapter ³³ HP Smart 45 W External AC power adapter ³³ HP Smart 45 W USB Type-C® adapter ³³

Primary Battery

HP Long Life 3-cell, 45 Wh Polymer³⁴

Power Cord

3-wire plug - 1m ³³ 2-wire plug - 1m ³³

Battery life

Up to 12 hours and 30 minutes (UMA graphics, Intel® 11th generation CPU and 3-cell 45 WHr battery)

Battery Weight

190 q

- 33. Availability may vary by country.
- 34. Battery is internal and not replaceable by customer. Serviceable by warranty.

WEIGHTS & DIMENSIONS

Product Weight 35

Starting at 3.83 lb Starting at 1.74 kg

Product Dimensions (w x d x h)

35.94 x 23.39 x 1.99 cm 14.15 x 9.21 x 0.78 in



Technical Specifications

35. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 SuperSpeed USB Type-C[®] 10Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)

3 SuperSpeed USB Type-A 5Gbps signaling rate (1 charging, 1 powered port)

1 HDMI 1.4b 37

1 RJ-45

1 Headphone/microphone combo jack

1 AC power

Expansion Slots

1 Micro SD Card Reader Supports SD, SDHC, SDXC

37. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90-day software limited warranty options depending on country. Batteries have a default one-year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.38

38. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations System Configuration	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: •IT ECO declaration •US ENERGY STAR® •EPEAT® 2019 Gold in U.S. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information. The configuration used for the Energy Consumption and Declared Noise Emissions data for the			
	Notebook model is based on a "Ty	pically Configured Notebook".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	4.14 W	4.164 W	4.056 W	
Normal Operation (Long idle)	2.112 W	2.184 W	2.076 W	
Sleep	0.372 W	0.384 W	0.372 W	
Off	0.192 W	0.228 W	0.192 W	
Heat Dissipation*	Microsoft Windows® operating sys	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	14 BTU/hr	14 BTU/hr	14 BTU/hr	
Normal Operation (Long idle)	7 BTU/hr	7 BTU/hr	7 BTU/hr	
Sleep	1 BTU/hr	1 BTU/hr	1 BTU/hr	
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr	
	Heat dissipation is calculated base for one hour.	ed on the measured watts, assun	ning the service level is attained	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	2.6		14.4	
Fixed Disk – Random writes	2.6		14.4	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 3 USB ports • 1 PC card slot (type I/II)			



Technical Specifications

<u>-</u>	ations			
	• 1 ExpressCard/54 slot			
	• 1 IEEE 1394 Port			
	• 2 SODIMM memory slots			
	Optional expansion base docking station			
	• 1 multi-bay II storage port			
	Interchangeable HDD			
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of			
	production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC		
	Batteries use	ed in the product do not contain:		
	Mercury grea	ater the1ppm by weight		
	Cadmium gre	eater than 20ppm by weight		
	Battery size:	Not Applicable		
	Battery type	: Not Applicable		
Additional Information	This produ	ct is in compliance with the Restrictions of Hazardous S	ubstances (RoHS) directive -	
	2011/65/EC.			
	• This HP pro	oduct is designed to comply with the Waste Electrical and	Electronic Equipment (WEEE)	
	Directive – 2		4-1	
			alifornia: Safe Drinking Water	
	• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).			
	• This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <gold> level, see</gold>			
	http://www.epeat.net			
	• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.			
	This product contains 2.4% post-consumer recycled plastic (by wt.) This product is 96.2% recycle, able when properly disposed of at and of life.			
	• This product is 96.2% recycle-able when properly disposed of at end of life.			
Packaging Materials	External:	PAPER/Paper	51 g	
		PAPER/Corrugated	230 g	
	Internal:	PLASTIC/Polyethylene Expanded - EPE	31 g	
		PLASTIC/Polyethylene low density - LDPE	9 g	
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer			
	to the HP Ger	neral Specification for the Environment at		
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):			
	• Asbestos			
	Certain Azo Colorants			
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Codmium			
	• Cadmium			
	Chlorinated Hydrocarbons			
	Chlorinated Paraffins			
	• Formaldehyde			
	Halogenate	ed Diphenyl Methanes		



Technical Specifications

•	ations
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental Information	Global Citizenship Report
intormation	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications http://www.s.bp.com/us/on/bp.information/onvironment/osolabels.html
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC

Power)

Nominal Operating Voltage 19 V
Average Operating Power 4.86W
Integrated graphics Yes

Discrete Graphics N18S-G5 : 25W

Max Operating Power Discrete < 65W

UMA < 45W

Temperature

Operating 32° to 95° F (0° to 35° C) Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms Non-operating 1.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m) Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard

Certifications

UL Yes
CSA Yes
FCC Compliance Yes

ENERGY STAR® Select models 38

EPEAT® 2019 Gold in U.S. 39

Yes

ICES Yes Australia / Yes NZ A – Tick Compliance Yes CCC Yes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marketing Compliance** Yes **BNCI or BELUS** Yes CIT Yes



GOST

Technical Specifications

Saudi Arabian Compliance (ICCP)

Yes
SABS

Yes

38.Configurations of the HP ProBook 450 G8 that are ENERGY STAR® certified are identified as HP ProBook 450 G8 ENERGY STAR on HP websites and on http://www.energystar.gov.

39. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.



Technical Specifications

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Actual brightness will be lower with touchscreen or Sure View.

Panel LCD 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA 45% NTSC 250nits eDP 1.2 w/o PSR bent NWBZ

 Outline Dimensions (W x H x D)
 350.96 x 205.54 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 370 g (max)
Diagonal Size 15.6 inch

Thickness 3.0 mm/ 5.0 mm (w/PCB) (max)

InterfaceeDP 1.2 (2 lane)Surface TreatmentAnti-Glare

Touch Enabled No

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Stripe
Backlight LED
Color Gamut Coverage NTSC 45%

Color Depth 6 bits (Hi FRC supportive w/ condition to enable)

Viewing Angle UWVA 85/85/85

Panel LCD 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA 45% NTSC 250nits eDP 1.2 w/o PSR bent Touch on Panel NWBZ

 Outline Dimensions (W x H x D)
 350.96 x 205.74 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 380 g (max)
Diagonal Size 15.6 inch

Thickness 3.2mm/ 5.2mm (PCB) (max)

Interface eDP 1.2

Surface Treatment Anti-Glare On-cell

Touch Enabled Yes

Contrast Ratio 600:1 (typ.)
Refresh Rate 60 Hz
Brightness 250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Stripe
Backlight LED
Color Gamut Coverage NTSC 45%
Color Depth 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 15.6 inch FHD (1920x1080) Anti-Glare WLED UWVA sRGB 100% NTSC 400nits eDP 1.4+PSR2 bent LP NWBZ

 Outline Dimensions (W x H x D)
 349.46 x 204.79 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 325 g (max)
Diagonal Size 15.6 inch

Thickness 2.6mm / 4.6mm (PCB) (max)

Interface eDP 1.4
Surface Treatment Anti-Glare
Touch Enabled No

Contrast Ratio 1200:1 (typ.)

Refresh Rate 60 Hz Brightness 400 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Stripe

Backlight LED

Color Gamut CoveragesRGB 100%Color Depth8 bit

Viewing Angle UWVA 85/85/85

Panel LCD 15.6-in FHD (1920x1080) Anti-Glare WLED UWVA 72% NTSC 1000nits eDP 1.4+PSR2 PrivacyG3 NWBZ bent

 Outline Dimensions (W x H x D)
 349.52x 205.39 mm (max)

 Active Area
 344.16 x 193.59 mm (typ.)

Weight 350 g (max)
Diagonal Size 15.6 inch

Thickness 2.6mm / 4.5mm Max. (PCB side)

Interface eDP 1.4 + PSR (4 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio2000:1 (typ.)Refresh Rate60 HzBrightness1000 nits

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Backlight LED

Color Gamut Coverage SRGB 100%

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Technical Specifications

Panel LCD 15.6-in HD (1366x768) Anti-Glare WLED SVA 45% NTSC 250nits eDP 1.2 w/o PSR NWBZ bent

 Outline Dimensions (W x H x D)
 350.96 x 205.54 (mm) max

 Active Area
 344.23 x 193.54 mm (typ.)

Weight 370 g max Diagonal Size 15.6 inch

Thickness 3.2mm (panel) / 5.0mm (panel+PCB) max

InterfaceeDP 1.2 (1 lane)Surface TreatmentAnti-Glare

Touch Enabled No

Contrast Ratio300:1 (typ)Refresh Rate60 HzBrightness250nits

Pixel Resolution 1366 x 768 (HD)

Format RGB

Backlight LED

Color Gamut Coverage NTSC 45%

Color Depth 6 bits

Viewing Angle SVA 45/45/15/35



Technical Specifications

STORAGE AND DRIVES*

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128GB 2280 PCIe-3x2 Three Layer Cell

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe

Maximum Sequential Read 1400 ~ 2100 MB/s

Maximum Sequential Write 800 ~ 1200 MB/s

Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security; DIPM; TRIM; DEVSLP

SSD 1TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided

Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

Height 0.09 in (2.3 mm)

Width 0.87 in (22 mm)

Weight 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4

Maximum Sequential Read 3100 ~ 3500 MB/s

Maximum Sequential Write 2770 ~ 3037 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 256GB 2280 PCIe NVMe Form Factor Value

Form Factor M.2 2280
Capacity 256 GB
NAND Type Value

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe Gen3
Maximum Sequential Read 2100 ~ 2200 MB/s



Technical Specifications

Maximum Sequential Write 900 ~ 1400 MB/s Logical Blocks 500.118.192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security (optional); TRIM; L1.2

SSD 512GB 2280 PCIe NVMe

Value

Form Factor M.2 2280
Capacity 512 GB
NAND Type Value

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface PCIe NVMe Gen3
Maximum Sequential Read 2200 ~ 2300 MB/s
Maximum Sequential Write 1000 ~ 1600 MB/s
Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security (optional); TRIM; L1.2

SSD 512GB 2280 PCIe-3x2x2 NVMe+SSD 32GB 3D Xpoint

Form Factor M.2 2280 Capacity 512 GB

NAND Type QLC+3D XPoint
Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)

Interface PCIe NVMe Gen3X2X2

Maximum Sequential Read Up to 2400 MB/s

Maximum Sequential Write Up to 1300 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

Intel Wi-Fi® 6¹ AX201 + Bluetooth® 5 (802.11ax 2x2, non-vPro®, supporting gigabit file transfer speeds)⁵

non-vPro®

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h
IEEE 802.11h

IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability

Features Wi-Fi® 6 technology

Frequency Band

802.11b/g/n/ax
 2.402 – 2.482 GHz
 802.11a/n/ac/ax
 4.9 – 4.95 GHz (Japan)
 5.15 – 5.25 GHz
 5.25 – 5.35 GHz
 5.47 – 5.725 GHz

5.825 - 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

I 6UMHZ)

802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³

• IEEE compliant 64 /128-bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationWPA3 certificationIEEE 802.11iWAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

• 802.11b: +18.5dBm minimum

802.11b: +18.5dBm minimum
802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum



802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption

• Transmit mode: 2.0 W

• Receive mode:1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

· Radio disabled: 8 mW

Power Management

ACPI and PCI Express compliant power management 802.11 compliant

power saving mode

Receiver Sensitivity³

802.11b, 1Mbps: -93.5dBm maximum
802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum

802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum
802.11ax, MCS11(HT40): -59dBm maximum

• 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type

High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8 g

2. Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF

LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology



Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate* 2.17 Mbps

BLE: 1 Mbps signaling data rate * 0.2 Mbps

*. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported **Link Topology** Microsoft Windows Bluetooth Software

Power Management

Microsoft Windows ACPI, and USB Bus Support Certifications

FCC (47 CFR) Part 15C. Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it

may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.



Technical Specifications

- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).
- 4. Wi-Fi supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160MHz channels.

Intel Jefferson Peak2
9560 802.11a/b/g/n/ac
(2x2) Wi-Fi and
Bluetooth® 5.0 Combo ¹
non-vPro®

Wireless LAN Standards	EEE 802.11a
------------------------	-------------

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h
IEEE 802.11h
IEEE 802.11h
IEEE 802.11r
IEEE 802.11r
IEEE 802.11v

Interoperability

Wi-Fi® CERTIFIED modules

Frequency Band

802.11b/g/n
 2.402 – 2.482 GHz
 802.11a/n/ac

4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz

5.47 – 5.725 GHz 5.825 – 5.850 GHz

Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

 \bullet 802.11ac: MCS0 \sim MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³ • IEEE and WiFi compliant 64 / 128-bit WEP encryption for

IEEE and WiFi compliant 64 / 128-bit WEP encryption for a/b/g mode only
 AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationWPA3 certificationIEEE 802.11i

WAPI

Technical Specifications

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

802.11b: +18.5dBm minimum
802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum

• 802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption

• Transmit mode: 2.0 W

Receive mode:1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
 Idle mode: 50 mW (WLAN unassociated)
 Connected Standby/Modern Standby: 10mW

· Radio disabled: 8 mW

Power Management

ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴

802.11b, 1Mbps: -93.5dBm maximum
802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum

802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum

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Weight 1. Type 2230: 2.8 g

2. Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

Technical Specifications

LED Activity LED Amber – Radio OFF

LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Leg

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate* throughput up to 2.17 Mbps

BLE: 1 Mbps signaling data rate* throughput up to 0.2 Mbps

* Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

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a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management

Certifications

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

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Certifications

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LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8822CE	Wireless LAN Standards	IEEE 802.11a
802.11ac 2x2 Wi-Fi + Bluetooth® 5		IEEE 802.11b
		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi® CERTIFIED modules
	Frequency Band	• 802.11b/g/n
		2.402 – 2.482 GHz
		• 802.11a/n/ac
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz
		5.25 – 5.35 GHz
		5.47 – 5.725 GHz
		5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
		• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
		 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &
		160MHz)
	Modulation	Direct Sequence Spread Spectrum
		BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	• IEEE and WiFi compliant 64 / 128-bit WEP encryption for a/b/g mode only
	-	AES-CCMP: 128 bit in hardware
		• 802.1x authentication
		• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
		WPA2 certification
		WPA3 certification
		• IEEE 802.11i



Technical Specifications

• WAPI

Network Architecture

Models Roaming Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

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802.11ac VHT80(5GHz): +11.5dBm minimum
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Power Consumption • Transmit mode: 2.0 W

• Receive mode: 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

· Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ • 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

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Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

Technical Specifications

LED Activity LED Amber – Radio OFF

LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

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BLE: 1 Mbps signaling data rate* throughput up to 0.2 Mbps

* Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

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Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management

Certifications

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Wi-Fi® supporting gigabit speeds is achievable when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 160 MHz channels.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).

Intel®	XMM™	7360	LTE-
Advan	red		

Technology/Operating F

FDD LTE:

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (Band 4),

850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12),

700 (Band 13)

700 (Band 17), 850 (Band 18), 850 (Band 19), 800 (Band 20), 1450 (Band

21), 850 (Band 26)

700 (Band 28) MHz, 700 (Band 29), 2300 (Band 30), 2100 (Band 66) MHz

TDD LTE:

2600 (Band 38), 1900 (Band 39), 2300 (Band 40), 2500 (Band 41) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900

(Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 ± 2.046 MHz

Maximum data rates LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions (Length x Width x Thickness) 42 x 30 x 2.3 mm

Connector RJ-45

System Interface PCIe + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

Realtek RTK8111EPH 10/100/1000 Integrated NIC 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-

30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Performance TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Power consumption Cable Disconnetion: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

Power ACPI compliant – multiple power modes

Management Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

:lause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Security & Manageability RTK DASH support with appropriate RTK chipset components



POWER

AC Adapter 45 Watt nPF Standard USB Type-C[®] Straight 1.8m

AC Adapter 45 Watt nPFC Dimensions (H x W x D)

Input

94.0mm x 40.0mm x 26.5mm

Weight 192.5g +/-10%

Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 5V/15W

9V/27W 12V/36W 15V/45W

DC output 5V/9V/12V/15V

Hold-up time 5 ms at 115 Vac input

Connector USB Type-C®

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart Dimensions nPFC Standard Barrel 4.5mm Right Angle 1.8m

 Dimensions
 95 x 45 x 26.8 mm

 Weight
 200 g +/- 10 g

Input Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45 W

DC output 19.5 V

Hold-up time 5 ms at 115 Vac input

Output current limit <8.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity20% to 95%Storage Humidity10% to 95%

EMI and Safety

CE Mark - full compliance with LVD and EMC directives

Certifications

Worldwide safety standards - IEC60950, EN60950, LIL

tions Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart Dimensions nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong Input

 Dimensions
 95 x 45 x 26.8 mm

 Weight
 200 q +/- 10 q

Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45 W

DC output 19.5 V

Hold-up time 5 ms at 115 Vac input

Output current limit <8.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

Input

CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Standard USB Type-C[®] Straight 1.8m
 Dimensions
 90.0 x 51 x 28.5mm

 Weight
 250 g +/- 10 g

Input Efficiency 81.5% min at 115 Vac/ 230 Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A

89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output Output power 65 W

DC output 5V/9V/12V/15V/20V **Hold-up time** 5 ms at 115 Vac input

Output current limit 8.0A Max.

Connector USB Type C[®]

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt Smart Dimensions (H x W x D) nPFC EM Barrel 4.5mm

New EM

 Dimensions (H x W x D)
 102 x 55 x 30mm

 Weight
 250g +/-10%

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65W

DC output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

Technical Specifications

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.



AC Adapter 65 Watt Smart nPFC Standard Barrel

Dimensions (H x W x D) 4.5mm Right Angle 1.8m 90 x 51 x 28.5mm

> Weight 230g +/-10%

Input **Input Efficiency** 88.0 % at 115 Vac and 89.0 % at 230 Vac

> Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output **Output power** 65W

> **DC** output 19.5V

Hold-up time 5 ms at 115 Vac input

Output current limit <11.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety CE Mark - full compliance with LVD and EMC directives

Certifications Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

Battery RH 3 Cell WHr 45 Long Life -PL Fast Charge Dimensions (H x W x L) 6.2 x 68.7 x 249.6mm

Weight 190q

Cells/Type 3cell Lithium-Ion Polymer cell/ 545974

Voltage 11.4 V Amp-hour capacity 3.950Ah **Watt-hour capacity** 45 Wh

Operating (Charging) 32° to 113° F (0° to 45° C) Operating (Discharging) 14° to 122° F (-10° to 60° C)

Optional Travel Battery

Available

Warranty Based on system offering



HP ProBook 450 G8 Notebook PC

QuickSpecs

Technical Specifications

Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Business Backpack (up to 17.3")	2SC67AA
	HP Business Case (up to 15.6")	2SC66AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Recycled Top Load	5KN29AA
	HP Recycled Backpack	5KN28AA
Docking	HP USB-C® Mini Dock	1PM64AA
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	
	HP USB-C/A Universal Dock G2	3AQ21AA 5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Wired Desktop 320MK Mouse & Keyboard	9SR36AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP USB Travel Mouse	G1K28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub G2	7PJ38AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP Stereo USB Headset	T1A67AA
	HP Stereo 3.5mm Headset	T1A66AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W USB-C LC Power Adapter	TBD
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Options and Accessories (sold separately and availability may vary by country)

HP Power Bank N9F71AA

HP USB-C Notebook Power Bank 3TB55AA

Storage HP External USB Optical Drive F2B56AA

Security HP Sure Key Cable Lock 6UW42AA

HP Nano Keyed Cable Lock 1AJ39AA



Summary of Changes

Date of change:	Version History:		Description of change:
December 14, 2020	V1 to V2	Update	USB Information
January 17, 2021	V2 to V3	Update	Environmental Data
January 21, 2021	V3 to V4	Added	WPA3 certification in Security, Networking section
January 26, 2021	V4 to V5	Added	New Processors and USB Ports
January 29, 2021	V5 to V6	Update	USB Ports
February 2, 2021	V6 to V7	Update	Noise Emissions Data
	V7 to V8		

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